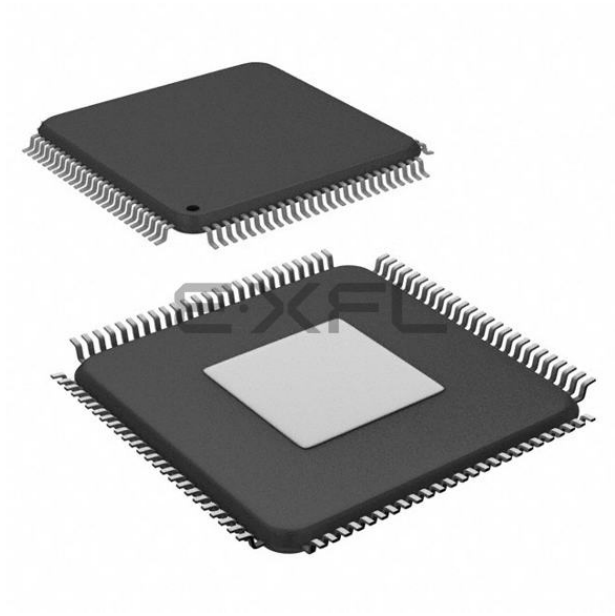
Infineon Technologies - XC226796F66LACKXUMA1 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	C166SV2
Core Size	16/32-Bit
Speed	66MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	DMA, I²S, POR, PWM, WDT
Number of I/O	75
Program Memory Size	768KB (768K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	82K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-3
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc226796f66lackxuma1

XC226x

16/32-Bit Single-Chip Microcontroller with 32-Bit Performance

Microcontrollers

Never stop thinking

Table 1 XC226x Derivative Synopsis

Derivative[1]	Temp. Range	Program Memory[2]	PSRAM[3]	CCU6 Mod.	ADC[4] Chan.	Interfaces[4]
SAK-XC2267-96FxxL	-40 °C to 125 °C	768 Kbytes Flash	64 Kbytes	0, 1, 2, 3	11 + 5	5 CAN Nodes, 6 Serial Chan.
SAF-XC2267-96FxxL	-40 °C to 85 °C	768 Kbytes Flash	64 Kbytes	0, 1, 2, 3	11 + 5	5 CAN Nodes, 6 Serial Chan.
SAK-XC2267-72FxxL	-40 °C to 125 °C	576 Kbytes Flash	32 Kbytes	0, 1, 2, 3	11 + 5	5 CAN Nodes, 6 Serial Chan.
SAF-XC2267-72FxxL	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1, 2, 3	11 + 5	5 CAN Nodes, 6 Serial Chan.
SAK-XC2267-56FxxL	-40 °C to 125 °C	448 Kbytes Flash	16 Kbytes	0, 1, 2, 3	11 + 5	5 CAN Nodes, 6 Serial Chan.
SAF-XC2267-56FxxL	-40 °C to 85 °C	448 Kbytes Flash	16 Kbytes	0, 1, 2, 3	11 + 5	5 CAN Nodes, 6 Serial Chan.
SAK-XC2264-96FxxL	-40 °C to 125 °C	768 Kbytes Flash	64 Kbytes	0, 1	8	2 CAN Nodes, 4 Serial Chan.
SAF-XC2264-96FxxL	-40 °C to 85 °C	768 Kbytes Flash	64 Kbytes	0, 1	8	2 CAN Nodes, 4 Serial Chan.
SAK-XC2264-72FxxL	-40 °C to 125 °C	576 Kbytes Flash	32 Kbytes	0, 1	8	2 CAN Nodes, 4 Serial Chan.
SAF-XC2264-72FxxL	-40 °C to 85 °C	576 Kbytes Flash	32 Kbytes	0, 1	8	2 CAN Nodes, 4 Serial Chan.
SAK-XC2264-56FxxL	-40 °C to 125 °C	448 Kbytes Flash	16 Kbytes	0, 1	8	2 CAN Nodes, 4 Serial Chan.
SAF-XC2264-56FxxL	-40 °C to 85 °C	448 Kbytes Flash	16 Kbytes	0, 1	8	2 CAN Nodes, 4 Serial Chan.

1) This Data Sheet is valid for devices starting with and including design step AC.

2) Specific inormation about the on-chip Flash memory in **Table 2**.

3) All derivatives additionally provide 1 Kbyte SBRAM, 2 Kbytes DPRAM, and 16 Kbytes DSRAM.

4) Specific information about the available channels in **Table 3**.
Analog input channels are listed for each Analog/Digital Converter module separately (ADC0 + ADC1).

2 General Device Information

The XC226x derivatives are high-performance members of the Infineon XC2000 Family of full-feature single-chip CMOS microcontrollers. These devices extend the functionality and performance of the C166 Family in terms of instructions (MAC unit), peripherals, and speed. They combine high CPU performance (up to 80 million instructions per second) with extended peripheral functionality and enhanced IO capabilities. Optimized peripherals can be adapted flexibly to meet the application requirements. These derivatives utilize clock generation via PLL and internal or external clock sources. On-chip memory modules include program Flash, program RAM, and data RAM.

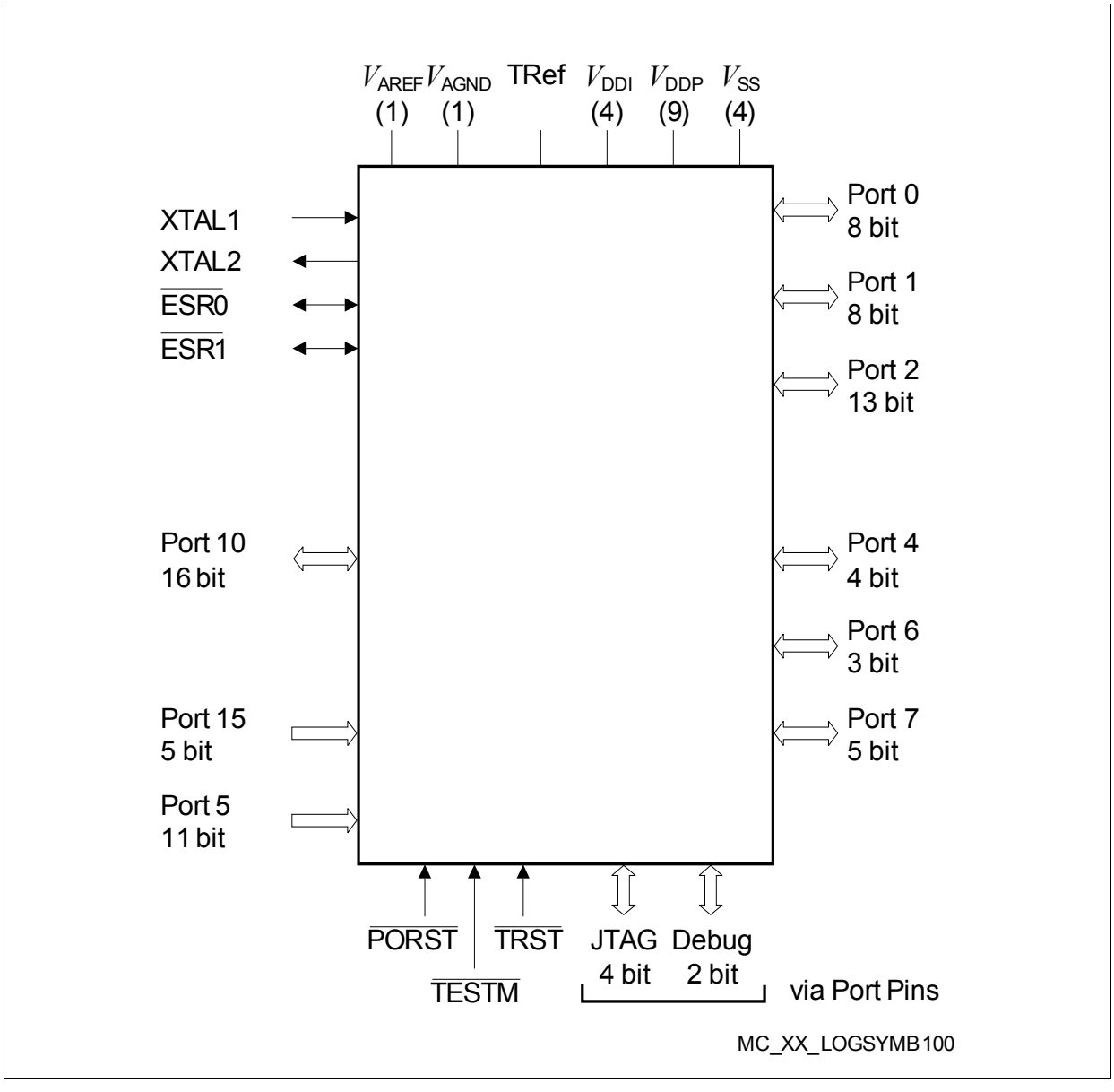

Figure 1 Logic Symbol

Notes to Pin Definitions

1. ***Ctrl.**: The output signal for a port pin is selected by bitfield PC in the associated register Px_IOCRy. Output O0 is selected by setting the respective bitfield PC to $1x00_B$, output O1 is selected by $1x01_B$, etc.*
   Output signal OH is controlled by hardware.
2. ***Type**: Indicates the pad type used (St=standard pad, Sp=special pad, DP=double pad, In=input pad, PS=power supply) and its power supply domain (A, B, M, 1).*

Table 4 Pin Definitions and Functions

Pin	Symbol	Ctrl.	Type	Function
3	$\overline{\text{TESTM}}$	I	In/B	**Testmode Enable** Enables factory test modes, must be held HIGH for normal operation (connect to V_{DDPB}). An internal pullup device will hold this pin high when nothing is driving it.
4	P7.2	O0 / I	St/B	**Bit 2 of Port 7, General Purpose Input/Output**
	EMUX0	O1	St/B	**External Analog MUX Control Output 0 (ADC1)**
	TxDC4	O2	St/B	**CAN Node 4 Transmit Data Output**
	CCU62_ CCPOS0A	I	St/B	**CCU62 Position Input 0**
	TDI_C	I	St/B	**JTAG Test Data Input**
5	$\overline{\text{TRST}}$	I	In/B	**Test-System Reset Input** For normal system operation, pin $\overline{\text{TRST}}$ should be held low. A high level at this pin at the rising edge of $\overline{\text{PORST}}$ activates the XC226x's debug system. In this case, pin $\overline{\text{TRST}}$ must be driven low once to reset the debug system. An internal pulldown device will hold this pin low when nothing is driving it.
6	P7.0	O0 / I	St/B	**Bit 0 of Port 7, General Purpose Input/Output**
	T3OUT	O1	St/B	**GPT1 Timer T3 Toggle Latch Output**
	T6OUT	O2	St/B	**GPT2 Timer T6 Toggle Latch Output**
	TDO_A	OH	St/B	**JTAG Test Data Output**
	ESR2_1	I	St/B	**ESR2 Trigger Input 1**
	RxDC4B	I	St/B	**CAN Node 4 Receive Data Input**

Table 6 XC226x Interrupt Nodes

Source of Interrupt or PEC Service Request	Control Register	Vector Location[1)]	Trap Number
CAPCOM Register 16, or ERU Request 0	CC2_CC16IC	xx'0040$_H$	10$_H$ / 16$_D$
CAPCOM Register 17, or ERU Request 1	CC2_CC17IC	xx'0044$_H$	11$_H$ / 17$_D$
CAPCOM Register 18, or ERU Request 2	CC2_CC18IC	xx'0048$_H$	12$_H$ / 18$_D$
CAPCOM Register 19, or ERU Request 3	CC2_CC19IC	xx'004C$_H$	13$_H$ / 19$_D$
CAPCOM Register 20, or USIC0 Request 6	CC2_CC20IC	xx'0050$_H$	14$_H$ / 20$_D$
CAPCOM Register 21, or USIC0 Request 7	CC2_CC21IC	xx'0054$_H$	15$_H$ / 21$_D$
CAPCOM Register 22, or USIC1 Request 6	CC2_CC22IC	xx'0058$_H$	16$_H$ / 22$_D$
CAPCOM Register 23, or USIC1 Request 7	CC2_CC23IC	xx'005C$_H$	17$_H$ / 23$_D$
CAPCOM Register 24, or ERU Request 0	CC2_CC24IC	xx'0060$_H$	18$_H$ / 24$_D$
CAPCOM Register 25, or ERU Request 1	CC2_CC25IC	xx'0064$_H$	19$_H$ / 25$_D$
CAPCOM Register 26, or ERU Request 2	CC2_CC26IC	xx'0068$_H$	1A$_H$ / 26$_D$
CAPCOM Register 27, or ERU Request 3	CC2_CC27IC	xx'006C$_H$	1B$_H$ / 27$_D$
CAPCOM Register 28, or USIC2 Request 6	CC2_CC28IC	xx'0070$_H$	1C$_H$ / 28$_D$
CAPCOM Register 29, or USIC2 Request 7	CC2_CC29IC	xx'0074$_H$	1D$_H$ / 29$_D$
CAPCOM Register 30	CC2_CC30IC	xx'0078$_H$	1E$_H$ / 30$_D$
CAPCOM Register 31	CC2_CC31IC	xx'007C$_H$	1F$_H$ / 31$_D$
GPT1 Timer 2	GPT12E_T2IC	xx'0080$_H$	20$_H$ / 32$_D$
GPT1 Timer 3	GPT12E_T3IC	xx'0084$_H$	21$_H$ / 33$_D$
GPT1 Timer 4	GPT12E_T4IC	xx'0088$_H$	22$_H$ / 34$_D$

Table 6 XC226x Interrupt Nodes (cont'd)

Source of Interrupt or PEC Service Request	Control Register	Vector Location[1)]	Trap Number
GPT2 Timer 5	GPT12E_T5IC	xx'008C$_H$	23$_H$ / 35$_D$
GPT2 Timer 6	GPT12E_T6IC	xx'0090$_H$	24$_H$ / 36$_D$
GPT2 CAPREL Register	GPT12E_CRIC	xx'0094$_H$	25$_H$ / 37$_D$
CAPCOM Timer 7	CC2_T7IC	xx'0098$_H$	26$_H$ / 38$_D$
CAPCOM Timer 8	CC2_T8IC	xx'009C$_H$	27$_H$ / 39$_D$
A/D Converter Request 0	ADC_0IC	xx'00A0$_H$	28$_H$ / 40$_D$
A/D Converter Request 1	ADC_1IC	xx'00A4$_H$	29$_H$ / 41$_D$
A/D Converter Request 2	ADC_2IC	xx'00A8$_H$	2A$_H$ / 42$_D$
A/D Converter Request 3	ADC_3IC	xx'00AC$_H$	2B$_H$ / 43$_D$
A/D Converter Request 4	ADC_4IC	xx'00B0$_H$	2C$_H$ / 44$_D$
A/D Converter Request 5	ADC_5IC	xx'00B4$_H$	2D$_H$ / 45$_D$
A/D Converter Request 6	ADC_6IC	xx'00B8$_H$	2E$_H$ / 46$_D$
A/D Converter Request 7	ADC_7IC	xx'00BC$_H$	2F$_H$ / 47$_D$
CCU60 Request 0	CCU60_0IC	xx'00C0$_H$	30$_H$ / 48$_D$
CCU60 Request 1	CCU60_1IC	xx'00C4$_H$	31$_H$ / 49$_D$
CCU60 Request 2	CCU60_2IC	xx'00C8$_H$	32$_H$ / 50$_D$
CCU60 Request 3	CCU60_3IC	xx'00CC$_H$	33$_H$ / 51$_D$
CCU61 Request 0	CCU61_0IC	xx'00D0$_H$	34$_H$ / 52$_D$
CCU61 Request 1	CCU61_1IC	xx'00D4$_H$	35$_H$ / 53$_D$
CCU61 Request 2	CCU61_2IC	xx'00D8$_H$	36$_H$ / 54$_D$
CCU61 Request 3	CCU61_3IC	xx'00DC$_H$	37$_H$ / 55$_D$
CCU62 Request 0	CCU62_0IC	xx'00E0$_H$	38$_H$ / 56$_D$
CCU62 Request 1	CCU62_1IC	xx'00E4$_H$	39$_H$ / 57$_D$
CCU62 Request 2	CCU62_2IC	xx'00E8$_H$	3A$_H$ / 58$_D$
CCU62 Request 3	CCU62_3IC	xx'00EC$_H$	3B$_H$ / 59$_D$
CCU63 Request 0	CCU63_0IC	xx'00F0$_H$	3C$_H$ / 60$_D$
CCU63 Request 1	CCU63_1IC	xx'00F4$_H$	3D$_H$ / 61$_D$
CCU63 Request 2	CCU63_2IC	xx'00F8$_H$	3E$_H$ / 62$_D$
CCU63 Request 3	CCU63_3IC	xx'00FC$_H$	3F$_H$ / 63$_D$
CAN Request 0	CAN_0IC	xx'0100$_H$	40$_H$ / 64$_D$

3.7 Capture/Compare Units CCU6x

The XC226x features up to four CCU6 units (CCU60, CCU61, CCU62, CCU63).

The CCU6 is a high-resolution capture and compare unit with application-specific modes. It provides inputs to start the timers synchronously, an important feature in devices with several CCU6 modules.

The module provides two independent timers (T12, T13), that can be used for PWM generation, especially for AC motor control. Additionally, special control modes for block commutation and multi-phase machines are supported.

Timer 12 Features

- Three capture/compare channels, where each channel can be used either as a capture or as a compare channel.
- Supports generation of a three-phase PWM (six outputs, individual signals for high-side and low-side switches)
- 16-bit resolution, maximum count frequency = peripheral clock
- Dead-time control for each channel to avoid short circuits in the power stage
- Concurrent update of the required T12/13 registers
- Center-aligned and edge-aligned PWM can be generated
- Single-shot mode supported
- Many interrupt request sources
- Hysteresis-like control mode
- Automatic start on a HW event (T12HR, for synchronization purposes)

Timer 13 Features

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock
- Can be synchronized to T12
- Interrupt generation at period match and compare match
- Single-shot mode supported
- Automatic start on a HW event (T13HR, for synchronization purposes)

Additional Features

- Block commutation for brushless DC drives implemented
- Position detection via Hall sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC drives
- Output levels can be selected and adapted to the power stage

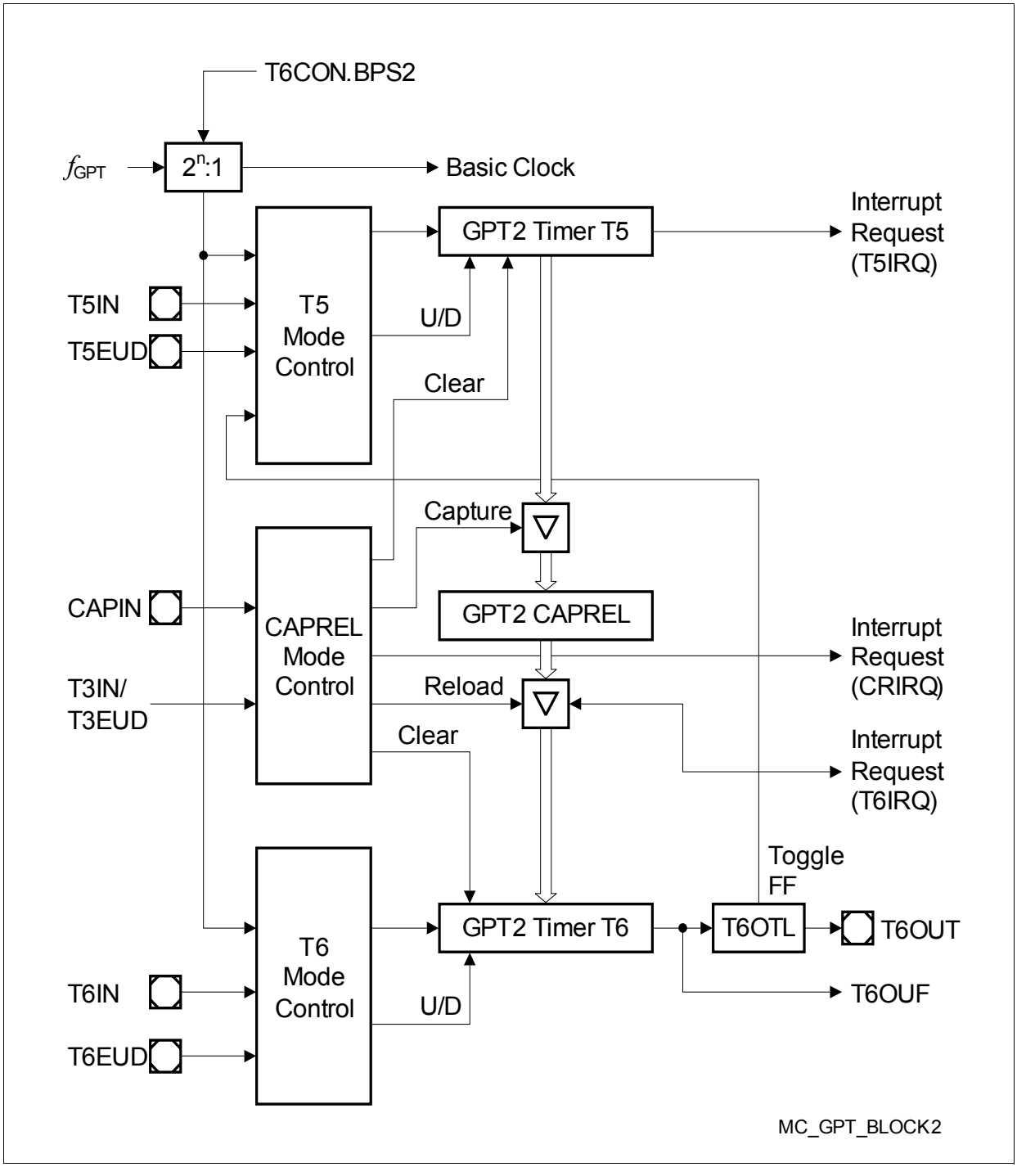

Figure 8 Block Diagram of GPT2

3.9 Real Time Clock

The Real Time Clock (RTC) module of the XC226x can be clocked with a clock signal selected from internal sources or external sources (pins).

The RTC basically consists of a chain of divider blocks:

- Selectable 32:1 and 8:1 dividers (on - off)
- The reloadable 16-bit timer T14
- The 32-bit RTC timer block (accessible via registers RTCH and RTCL) consisting of:
  - a reloadable 10-bit timer
  - a reloadable 6-bit timer
  - a reloadable 6-bit timer
  - a reloadable 10-bit timer

All timers count up. Each timer can generate an interrupt request. All requests are combined to a common node request.

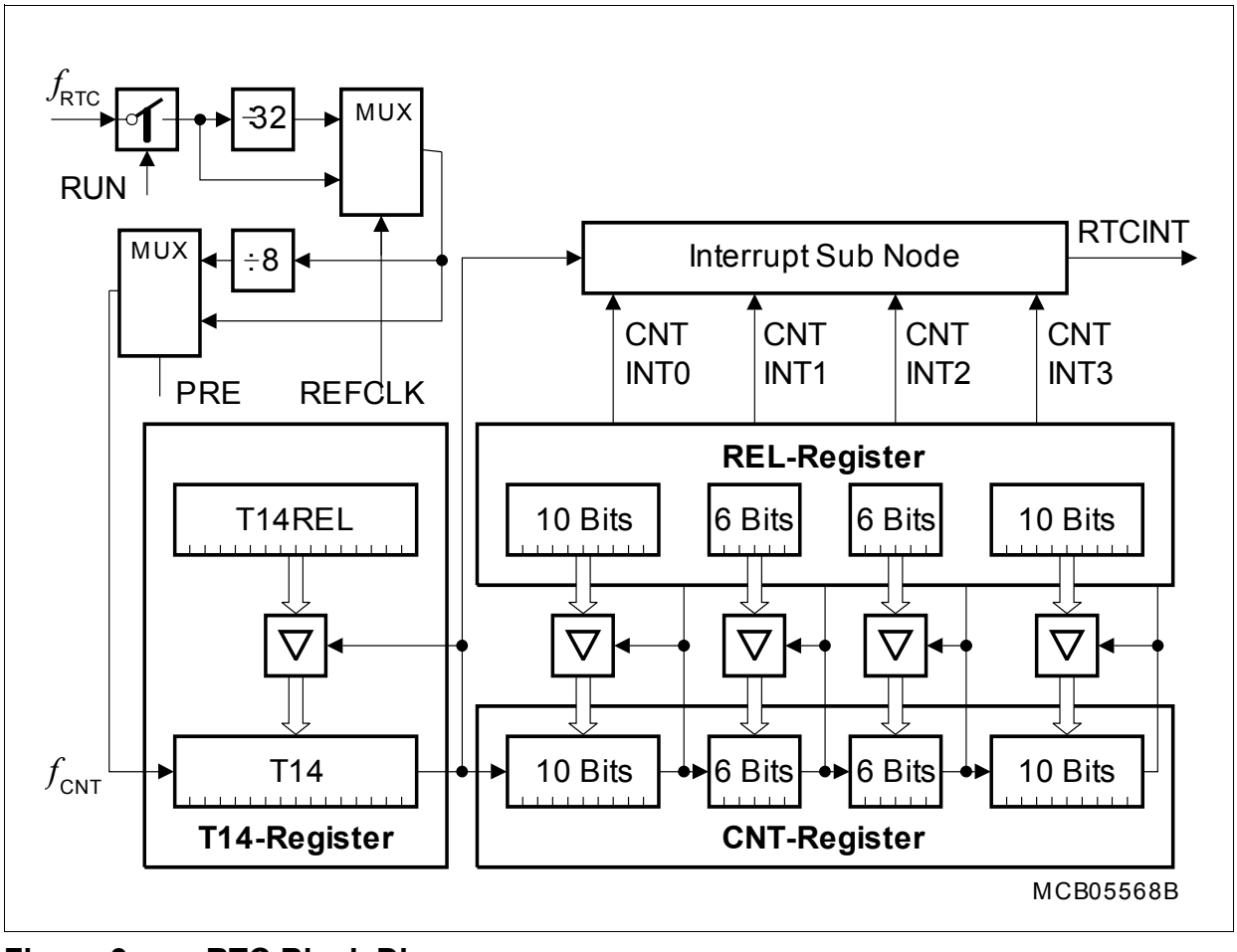

Figure 9 RTC Block Diagram

Note: The registers associated with the RTC are only affected by a power reset.

Target Protocols

Each USIC channel can receive and transmit data frames with a selectable data word width from 1 to 16 bits in each of the following protocols:

- **UART** (asynchronous serial channel)
  - maximum baud rate: f_{SYS} / 4
  - data frame length programmable from 1 to 63 bits
  - MSB or LSB first
- **LIN** Support (Local Interconnect Network)
  - maximum baud rate: f_{SYS} / 16
  - checksum generation under software control
  - baud rate detection possible by built-in capture event of baud rate generator
- **SSC/SPI/QSPI** (synchronous serial channel with or without data buffer)
  - maximum baud rate in slave mode: f_{SYS}
  - maximum baud rate in master mode: f_{SYS} / 2, limited by loop delay
  - number of data bits programmable from 1 to 63, more with explicit stop condition
  - MSB or LSB first
  - optional control of slave select signals
- **IIC** (Inter-IC Bus)
  - supports baud rates of 100 kbit/s and 400 kbit/s
- **IIS** (Inter-IC Sound Bus)
  - maximum baud rate: f_{SYS} / 2 for transmitter, f_{SYS} for receiver

Note: Depending on the selected functions (such as digital filters, input synchronization stages, sample point adjustment, etc.), the maximum achievable baud rate can be limited. Please note that there may be additional delays, such as internal or external propagation delays and driver delays (e.g. for collision detection in UART mode, for IIC, etc.).

MultiCAN Features

- CAN functionality conforming to CAN specification V2.0 B active for each CAN node (compliant to ISO 11898)
- Up to five independent CAN nodes
- Up to 128 independent message objects (shared by the CAN nodes)
- Dedicated control registers for each CAN node
- Data transfer rate up to 1 Mbit/s, individually programmable for each node
- Flexible and powerful message transfer control and error handling capabilities
- Full-CAN functionality for message objects:
  - Can be assigned to one of the CAN nodes
  - Configurable as transmit or receive objects, or as message buffer FIFO
  - Handle 11-bit or 29-bit identifiers with programmable acceptance mask for filtering
  - Remote Monitoring Mode, and frame counter for monitoring
- Automatic Gateway Mode support
- 16 individually programmable interrupt nodes
- Analyzer mode for CAN bus monitoring

Operating Conditions

The following operating conditions must not be exceeded to ensure correct operation of the XC226x. All parameters specified in the following sections refer to these operating conditions, unless otherwise noticed.

Table 12 Operating Condition Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Digital core supply voltage	V_{DDI}	1.4	–	1.6	V	
Core Supply Voltage Difference	ΔVDDI	-10	–	+10	mV	V_{DDIM} - V_{DDI1} 1)
Digital supply voltage for IO pads and voltage regulators, upper voltage range	V_{DDPA}, V_{DDPB}	4.5	–	5.5	V	2)
Digital supply voltage for IO pads and voltage regulators, lower voltage range	V_{DDPA}, V_{DDPB}	3.0	–	4.5	V	2)
Digital ground voltage	V_{SS}	0	–	0	V	Reference voltage
Overload current	I_{OV}	-5	–	5	mA	Per IO pin 3)4)
		-2	–	5	mA	Per analog input pin 3)4)
Overload positive current coupling factor for analog inputs 5)	K_{OVA}	–	1.0×10^{-6}	1.0×10^{-4}	–	$I_{OV} > 0$
Overload negative current coupling factor for analog inputs 5)	K_{OVA}	–	2.5×10^{-4}	1.5×10^{-3}	–	$I_{OV} < 0$
Overload positive current coupling factor for digital I/O pins 5)	K_{OVD}	–	1.0×10^{-4}	5.0×10^{-3}	–	$I_{OV} > 0$
Overload negative current coupling factor for digital I/O pins 5)	K_{OVD}	–	1.0×10^{-2}	3.0×10^{-2}	–	$I_{OV} < 0$
Absolute sum of overload currents	Σ|IOV|	–	–	50	mA	4)

2) Not subject to production test - verified by design/characterization. Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It cannot suppress switching due to external system noise under all conditions.
3) The maximum deliverable output current of a port driver depends on the selected output driver mode, see **Table 13, Current Limits for Port Output Drivers**. The limit for pin groups must be respected.
4) As a rule, with decreasing output current the output levels approach the respective supply level ($V_{OL} \rightarrow V_{SS}$, $V_{OH} \rightarrow V_{DDP}$). However, only the levels for nominal output currents are verified.
5) This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage is determined by the external circuit.
6) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. Please refer to the definition of the overload coupling factor K_{OV}.
7) The given values are worst-case values. In production test, this leakage current is only tested at 125°C; other values are ensured by correlation. For derating, please refer to the following descriptions:
   Leakage derating depending on temperature (T_J = junction temperature [°C]):
   I_{OZ} = 0.05 × $e^{(1.5 + 0.028 \times TJ)}$ [µA]. For example, at a temperature of 130°C the resulting leakage current is 8.54 µA.
   Leakage derating depending on voltage level (DV = V_{DDP} - V_{PIN} [V]):
   I_{OZ} = $I_{OZtempmax}$ - (1.6 × DV) [µA]
   This voltage derating formula is an approximation which applies for maximum temperature.
   Because pin P2.8 is connected to two pads (standard pad and high-speed clock pad), it has twice the normal leakage.
8) Keep current: Limit the current through this pin to the indicated value so that the enabled pull device can keep the default pin level: $V_{PIN} \geq V_{IH}$ for a pullup; $V_{PIN} \leq V_{IL}$ for a pulldown.
   Force current: Drive the indicated minimum current through this pin to change the default pin level driven by the enabled pull device: $V_{PIN} \leq V_{IL}$ for a pullup; $V_{PIN} \geq V_{IH}$ for a pulldown.
   These values apply to the fixed pull-devices in dedicated pins and to the user-selectable pull-devices in general purpose IO pins.
9) Not subject to production test - verified by design/characterization.
   Because pin P2.8 is connected to two pads (standard pad and high-speed clock pad), it has twice the normal capacitance.

Table 21 Coding of Bitfields LEVxV in Register SWDCON0

Code	Default Voltage Level	Notes[1)]
0000_B	2.9 V	
0001_B	3.0 V	LEV1V: reset request
0010_B	3.1 V	
0011_B	3.2 V	
0100_B	3.3 V	
0101_B	3.4 V	
0110_B	3.6 V	
0111_B	4.0 V	
1000_B	4.2 V	
1001_B	4.5 V	LEV2V: no request
1010_B	4.6 V	
1011_B	4.7 V	
1100_B	4.8 V	
1101_B	4.9 V	
1110_B	5.0 V	
1111_B	5.5 V	

1) The indicated default levels are selected automatically after a power reset.

Table 22 Coding of Bitfields LEVxV in Registers PVCyCONz

Code	Default Voltage Level	Notes[1)]
000_B	0.9 V	
001_B	1.0 V	
010_B	1.1 V	
011_B	1.2 V	
100_B	1.3 V	LEV1V: reset request
101_B	1.4 V	LEV2V: interrupt request
110_B	1.5 V	
111_B	1.6 V	

1) The indicated default levels are selected automatically after a power reset.

4.5 Flash Memory Parameters

The XC226x is delivered with all Flash sectors erased and with no protection installed.

The data retention time of the XC226x's Flash memory (i.e. the time after which stored data can still be retrieved) depends on the number of times the Flash memory has been erased and programmed.

Note: These parameters are not subject to production test but verified by design and/or characterization.

Table 23 Flash Characteristics (Operating Conditions apply)

Parameter	Symbol	Limit Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Programming time per 128-byte page	t_{PR}	–	3[1)]	3.5	ms	ms
Erase time per sector/page	t_{ER}	–	4[1)]	5	ms	ms
Data retention time	t_{RET}	20	–	–	years	1,000 erase / program cycles
Flash erase endurance for user sectors[2)]	N_{ER}	15,000	–	–	cycles	Data retention time 5 years
Flash erase endurance for security pages	N_{SEC}	10	–	–	cycles	Data retention time 20 years
Drain disturb limit	N_{DD}	64	–	–	cycles	3)

1) Programming and erase times depend on the internal Flash clock source. The control state machine needs a few system clock cycles. This requirement is only relevant for extremely low system frequencies.
In the XC226x erased areas must be programmed completely (with actual code/data or dummy values) before that area is read.

2) A maximum of 64 Flash sectors can be cycled 15,000 times. For all other sectors the limit is 1,000 cycles.

3) This parameter limits the number of subsequent programming operations within a physical sector. The drain disturb limit is applicable if wordline erase is used repeatedly. For normal sector erase/program cycles this limit will not be violated.

Access to the XC226x Flash modules is controlled by the IMB. Built-in prefetch mechanisms optimize the performance for sequential access.

Flash access waitstates only affect non-sequential access. Due to prefetch mechanisms, the performance for sequential access (depending on the software structure) is only partially influenced by waitstates.

4.6.2 Definition of Internal Timing

The internal operation of the XC226x is controlled by the internal system clock f_{SYS}.

Because the system clock signal f_{SYS} can be generated from a number of internal and external sources using different mechanisms, the duration of the system clock periods (TCSs) and their variation (as well as the derived external timing) depend on the mechanism used to generate f_{SYS}. This must be considered when calculating the timing for the XC226x.

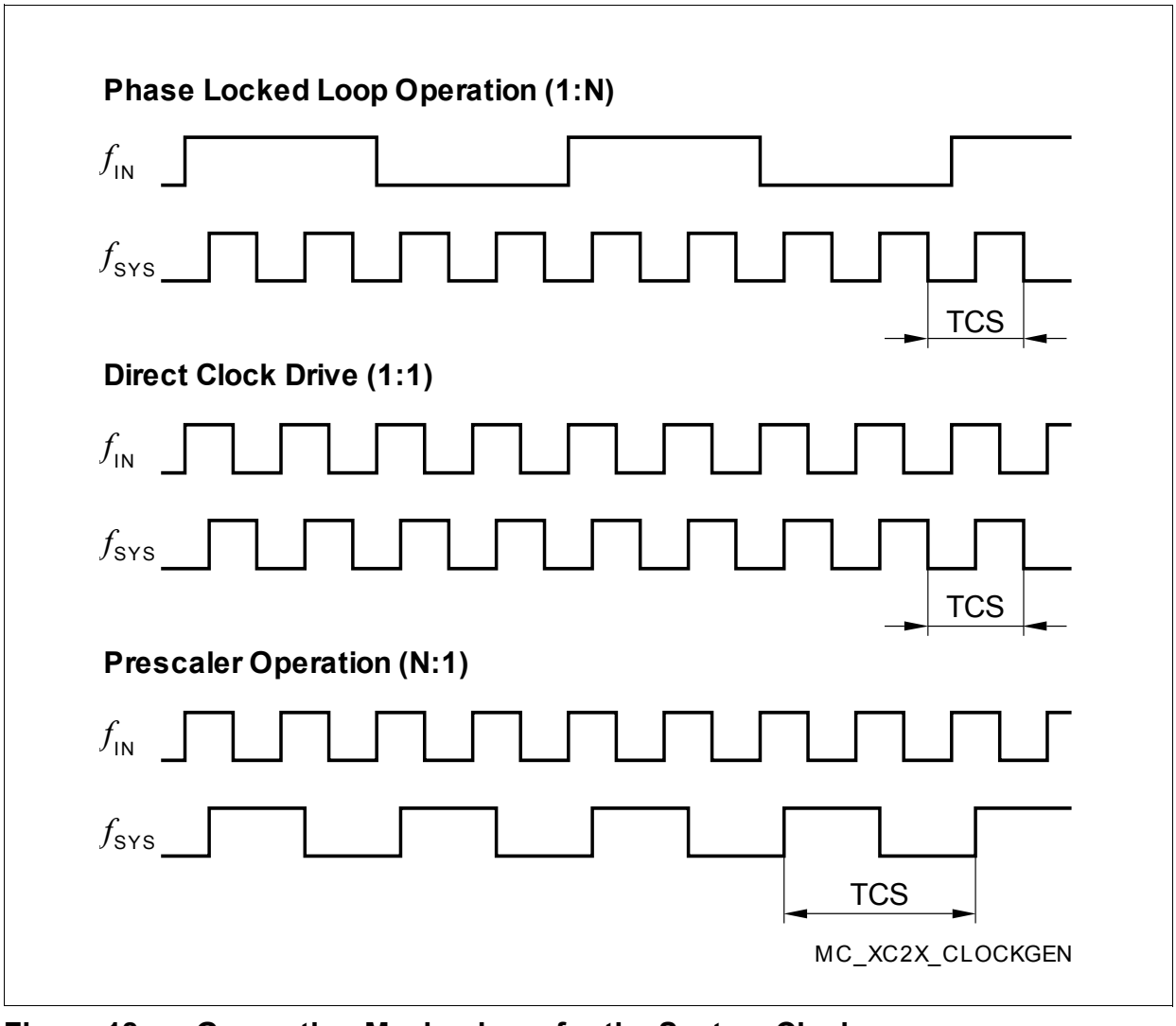

Figure 18 Generation Mechanisms for the System Clock

*Note: The example of PLL operation shown in **Figure 18** uses a PLL factor of 1:4; the example of prescaler operation uses a divider factor of 2:1.*

The specification of the external timing (AC Characteristics) depends on the period of the system clock (TCS).

Direct Drive

When direct drive operation is selected (SYSCON0.CLKSEL = 11_B), the system clock is derived directly from the input clock signal CLKIN1:

$f_{SYS} = f_{IN}$.

The frequency of f_{SYS} is the same as the frequency of f_{IN}. In this case the high and low times of f_{SYS} are determined by the duty cycle of the input clock f_{IN}.

Selecting Bypass Operation from the XTAL1[1)] input and using a divider factor of 1 results in a similar configuration.

Prescaler Operation

When prescaler operation is selected (SYSCON0.CLKSEL = 10_B, PLLCON0.VCOBY = 1_B), the system clock is derived either from the crystal oscillator (input clock signal XTAL1) or from the internal clock source through the output prescaler K1 (= K1DIV+1):

$f_{SYS} = f_{OSC}$ / K1.

If a divider factor of 1 is selected, the frequency of f_{SYS} equals the frequency of f_{OSC}. In this case the high and low times of f_{SYS} are determined by the duty cycle of the input clock f_{OSC} (external or internal).

The lowest system clock frequency results from selecting the maximum value for the divider factor K1:

$f_{SYS} = f_{OSC}$ / 1024.

Phase Locked Loop (PLL)

When PLL operation is selected (SYSCON0.CLKSEL = 10_B, PLLCON0.VCOBY = 0_B), the on-chip phase locked loop is enabled and provides the system clock. The PLL multiplies the input frequency by the factor **F** ($f_{SYS} = f_{IN} \times$ **F**).
F is calculated from the input divider P (= PDIV+1), the multiplication factor N (= NDIV+1), and the output divider K2 (= K2DIV+1):
(**F** = N / (P $\times$ K2)).

The input clock can be derived either from an external source at XTAL1 or from the on-chip clock source.

The PLL circuit synchronizes the system clock to the input clock. This synchronization is performed smoothly so that the system clock frequency does not change abruptly.

Adjustment to the input clock continuously changes the frequency of f_{SYS} so that it is locked to f_{IN}. The slight variation causes a jitter of f_{SYS} which in turn affects the duration of individual TCSs.

1) Voltages on XTAL1 must comply to the core supply voltage V_{DDI1}.

Table 29 External Bus Cycle Timing for Upper Voltage Range (Operating Conditions apply)

Parameter	Symbol	Limits			Unit	Note
		Min.	Typ.	Max.		
Output valid delay for: RD, WR(L/H)	t_{10} CC	–		13	ns	
Output valid delay for: BHE, ALE	t_{11} CC	–		13	ns	
Output valid delay for: A23 … A16, A15 … A0 (on P0/P1)	t_{12} CC	–		14	ns	
Output valid delay for: A15 … A0 (on P2/P10)	t_{13} CC	–		14	ns	
Output valid delay for: CS	t_{14} CC	–		13	ns	
Output valid delay for: D15 … D0 (write data, MUX-mode)	t_{15} CC	–		14	ns	
Output valid delay for: D15 … D0 (write data, DEMUX-mode)	t_{16} CC	–		14	ns	
Output hold time for: RD, WR(L/H)	t_{20} CC	0		8	ns	
Output hold time for: BHE, ALE	t_{21} CC	0		8	ns	
Output hold time for: A23 … A16, A15 … A0 (on P2/P10)	t_{23} CC	0		8	ns	
Output hold time for: CS	t_{24} CC	0		8	ns	
Output hold time for: D15 … D0 (write data)	t_{25} CC	0		8	ns	
Input setup time for: READY, D15 … D0 (read data)	t_{30} SR	18		–	ns	
Input hold time for: READY, D15 … D0 (read data)[1)]	t_{31} SR	-4		–	ns	

1) Read data are latched with the same internal clock edge that triggers the address change and the rising edge of RD. Address changes before the end of RD have no impact on (demultiplexed) read cycles. Read data can change after the rising edge of RD.

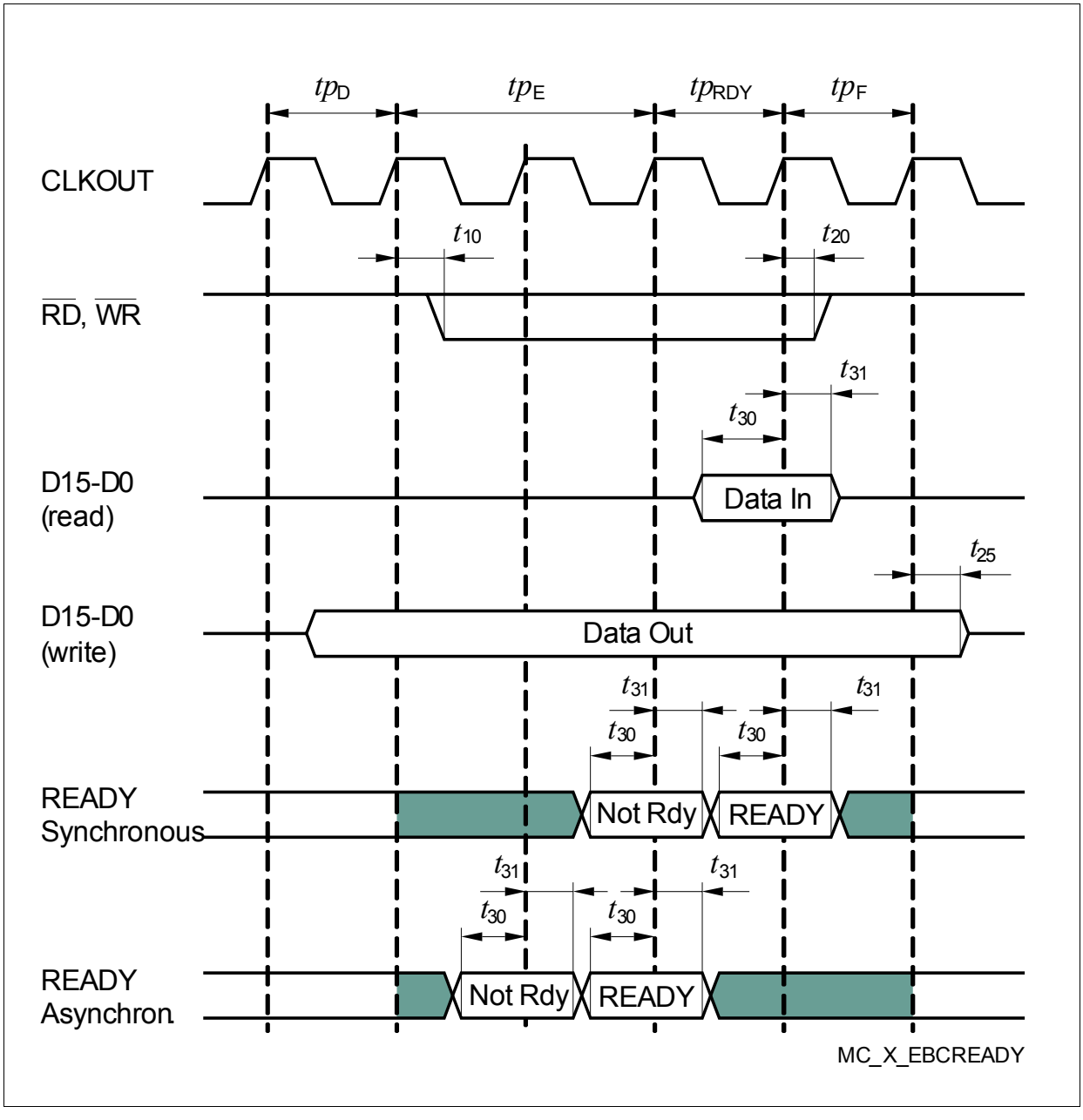

Figure 24 READY Timing

Note: If the READY input is sampled inactive at the indicated sampling point (“Not Rdy”) a READY-controlled waitstate is inserted (tpRDY),
sampling the READY input active at the indicated sampling point (“Ready”) terminates the currently running bus cycle.
Note the different sampling points for synchronous and asynchronous READY.
This example uses one mandatory waitstate (see tpE) before the READY input value is used.

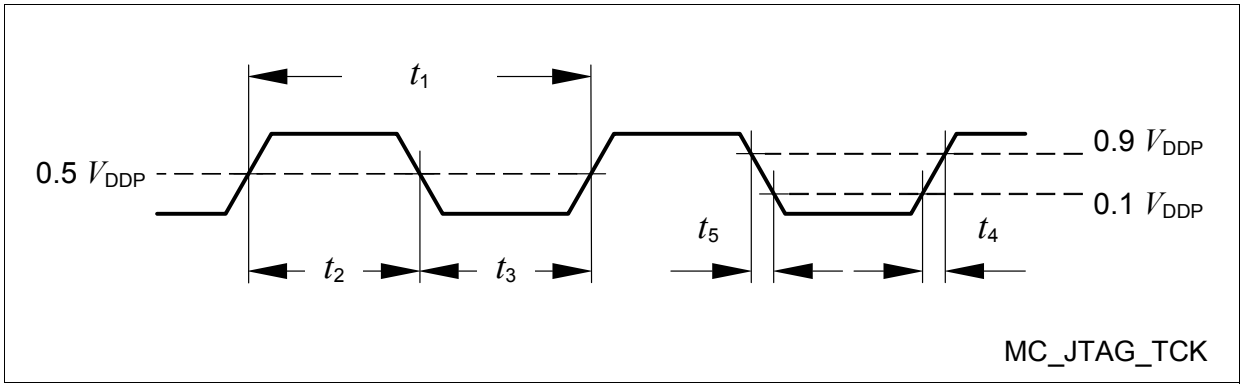

Figure 26 Test Clock Timing (TCK)

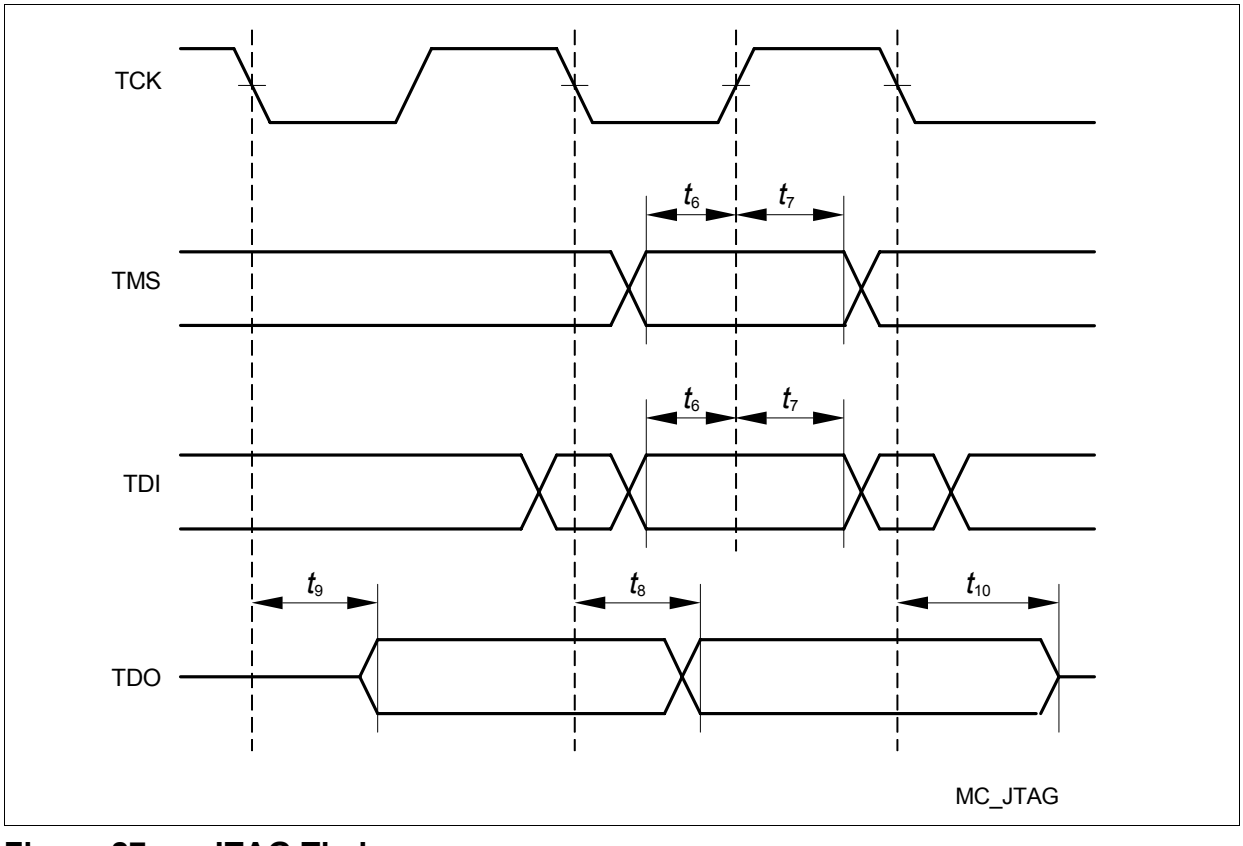

Figure 27 JTAG Timing